

В

PLATING

S = 0.38µm GOLD ON CONTACT ARFA 0.38µm GOLD ON TAIL

G = 0.76µm GOLD ON CONTACT AREA 0.76µm GOLD ON TAIL

F = 0.20µm GOLD ON CONTACT AREA

0.20µm GOLD ON TAIL T = 0.76 µm GOLD ON CONTACT AREA 2.54µm 100% MATTE TIN ON TAIL

H = GOLD FLASH ON CONTACT AREA

2.54µm 100% MATTE TIN ON TAIL

- I FAD FRFF (SFF NOTE II)

RETENTION (SEE NOTES 6 & 10) R: RETENTIVE LEG

STACKER HEIGHT (SEE NOTE 7)

- PACKAGING: - = BAGS (SEE NOTE 5) U = TUBES

-POSITIONS PFR ROW = "N" (02 TO 25)

PIN STYLF

22 24

26

28

30

32

34

36

38

40

42

OMIT FROM PRODUCT NUMBER FOR LEAD FREE WITH RETENTIVE LEG PRODUCT

OAL

08.2

09.6

10.2

11.8

13.5

14.1

15.6

17.1

19.1

21.1

18.0

NOTES:

I. MATERIAL HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL 94V-0, COLOR BLACK

PRODUCT NUMBER DESCRIPTION :

59132 - X XX - XX - XXX XLF

2. MATERIAL TERMINAL: COPPER ALLOY

(3) TO DETERMINE DIMENSIONS: N=NUMBER OF POSITIONS PER ROW EX.: $10 \text{ POS...} \text{ N} \times 2.00 = 20.00 \text{ TOTAL POSITIONS}$

4. 0.9kg MIN. PIN RETENTION IN EITHER DIRECTION.

5. PACKAGING;

(A) STANDARD PACKAGING: IN POLY BAGS.

(B) SPECIAL PACKAGING: IN TUBE. FOR ALL SPECIAL PACKAGING, FCI MUST BE CONTACTED FOR AVAILABILITY IN SIZE REQUESTED.

(6). RETENTION LEG:

2.3kg MAX INSERTION FORCE AND I kg MIN RETENTION FORCE PER RETENTIVE PIN USING 1.57 THICK CIRCUIT BOARD AND RECOMMENDED HOLE PATTERN. RETENTIVE LOCATION AT THE DISCRETION OF THE MANUFACTURER. RETENTION IS TWO PINS PER PART ADJACENT TO ONE ANOTHER.

- STACK HEIGHT IS DETERMINED BY CUSTOMER APPLICATION REQUIREMENTS, SPECIFIED IN mm. EXAMPLE: 3.7mm STACK HEIGHT=59132-XXX-XX-037X.
- POST LENGTH IS DETERMINED BY: (OAL)-(3.00)-(STACK HGT.) =POST LENGTH.MINIMUM MATING LENGTH TO BE 2.0mm.

- (9) DIM I.O APPLIES TO MOLDED SIDE(S) ONLY.IF SIDE(S) ARE BROKEN. DIM 1.5 MAX APPLIES.
- (10).OMIT FROM PRODUCT NUMBER IF FEATURE IS NOT APPLICABLE.
- (1). P/N:59132-XXXLF IS SAME AS P/N:59132-XXX. THE SUFFIX 'LF' IS ADDED FOR EASY LEAD FREE IDENTIFICATION.
- 12. THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- 13. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- 14. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- 15. A 🖒 SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.

dr			2010/10/31	projection			1111		size		scale		
eng			2014/10/29			MM		ecn no		5:	5 : ELX-N-19241-1		
chr			-							ELX-			
appr	Feagle Pan		2014/10/29	product family			MINITEK		rel level		Re	Released	
F	<u>Cj</u>	-	OMM UNSHI			ER		o ⊂ 50 * 0	5	9132)	re v	
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Pro/E File - REV C - 2009-06-09

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3 PDS: Rev :K

STATUS:Released

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